

OPTIMIZATION OF A MINIATURIZED ETHERNET 10 GBITS/S 8 CONDUCTORS INTERCONNECT FOR HARSH ENVIRONMENTS

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Design of a high speed Ethernet contact for military and aerospace industries



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Overview







Cat 6A criterions		Design optimization	
Insertion Loss (IL)		Low dielectric losses	F=[1MHz-500MHz]
Return Loss (RL)		Zc≈ 100Ω	
NEXT loss (NL)		Internal shielding	





- I. 2D-3D electromagnetic simulation approaches
- **II.** Prototype #1: validation of measurements & simulation tools
- **III.** Prototype #2: optimized Ethernet contact
- **IV.** Perspectives



□ Simulation using ANSYS HFSS 3D full wave solver □ BW = [10MHz, 1GHz]



2D-3D electromagnetic simulation approaches

[RLGC] matrix of every segment [8x8]

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$$[ABCD]_{i} = \begin{bmatrix} Y_{E}^{-1}{}_{i} * coshm(\Gamma_{i}) * Y_{E_{i}} & Z_{c_{i}}sinhm(\Gamma_{i}) \\ sinhm(\Gamma_{i}) * Z_{c}^{-1}{}_{i} & coshm(\Gamma_{i}) \end{bmatrix}$$

$$\Gamma_{i} = sqrtm(Y_{E_{i}} * Z_{M_{i}}) * l_{i} \qquad Y_{E_{i}} = G_{i} + j\omega C_{i}$$

$$Z_{c_i} = sqrtm(Y_E^{-1} * Z_{M_i}) \qquad \qquad Z_{M_i} = R_i + j\omega L_i$$

 l_i : segment length, $i \in [1,7]$

[ABCD]_i matrix of every segment [16x16]

$$[ABCD] = \prod_{i=1}^{7} [ABCD]_i$$

[ABCD] matrix of the contact [16x16]

2D-3D electromagnetic simulation approaches

[ABCD] single-ended matrix of the contact [16x16]

$$[S]_{se} = \begin{bmatrix} \{[A] + [B] * Z_0^{-1} - [C] * Z_0 - [D]\} * den^{-1} \\ 2 * den^{-1} \end{bmatrix} \\ den = [A] + [B] * Z_0^{-1} + [C] * Z_0 + [D] \end{bmatrix} \\ den = [A] + [B] * Z_0^{-1} + [C] * Z_0 + [D] \end{bmatrix}$$

$$[S]_{mm} = P_{mm} * [S]_{se} * P_{mm}^{-1} \\ [S]_{mm_{16X16}} = \begin{bmatrix} [S]_{dd_{8X8}} & [S]_{dc_{8X8}} \\ [S]_{cd_{8X8}} & [S]_{cc_{8X8}} \end{bmatrix}$$

[S] differential mode matrix of the contact [8x8]

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[S] :

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Prototype #1: validation of measurements & simulation tools



NEXT loss & Return loss measurement configuration Insertion loss measurement configuration





Diapositive 11

YB1 soudé = welded Younes Boujmad; 03/06/2019



The NEXT is in accordance with the category 6A standard

Complex assembling of the metal cross

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IL results: 2D segmentation approach \equiv 3D full wave simulation \equiv VNA measurement

The IL is not in accordance with the category 6A standard

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- \equiv VNA measurement
- RL level is 8.5 dB higher than the value imposed by the Ethernet cat 6A standard







□ TDR measurement: $60\Omega < Zc < 70\Omega$ for the contact #1







The first prototype doesn't meet the category 6A standard





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Prototype #2: optimized Ethernet contact

□ Optimization of the impedance matching by:

- > Including air gaps in the dielectric
- Modifying the shielding

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Decreasing the diameter of the pins



□ TDR measurement : $90\Omega < Zc < 100\Omega$ for the optimized contact (prototype #2)

Characteristic Impedance Optimization => Improves the IL and RL compared to the category 6A standard

Prototype #2: optimized Ethernet contact

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Integrating the shield in a single piece of dielectric

The NEXT in accordance with cat 6A

The optimized contact #2 is designed with a single piece of dielectric which facilitates contact assembly

- Broadband characterization of the dielectric polymer using coaxial lines [10 MHz - 12 GHz]
- □ Harsh environment qualification (temperatures and vibrations)
- □ Meet the industry standard for fabrication
- □ Conception of a mold for the dielectric part
- □ Final optimization leading to Ethernet #3 contact

THANK YOU FOR YOUR ATTENTION

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